

Customer Information Notification Update

202103003IU01: TJA1043ATK/0 Packing Change

Note: This notice is NXP Company Proprietary.

Issue Date: Mar 17, 2021 Effective date: Mar 18, 2021

Here is your personalized notification about a NXP general announcement.

For detailed information we invite you to view this notification online

Management summary

Product TJA1043ATK/0 packing will change to sealed drybag with dessicant, in line with the product's Moisture Sensitivity Level (MSL) 3.

Change Category

[]Wafer Fab Process	[]Assembly Process	[]Product Marking	[]Test Process	[]Design
[]Wafer Fab Materials	[]Assembly Materials	[]Mechanical Specification	[]Test Equipment	[]Errata
[]Wafer Fab Location	[]Assembly Location	[X]Packing/Shipping/Labeling	[]Test Location	[]Electrical spec./Test coverage
[]Eirmwaro	[]Other			

[]Firmware []Other

PCN Overview

Description

Product TJA1043ATK/0 was incorrectly not packed in a sealed drybag with dessicant. This will be corrected for products with datecode wk10 of 2021 onwards:

- The product name TJA1043ATK/0 will not change
- The last character of the orderable part number will change (TJA1043ATK/0Z => TJA1043ATK/0Y)
- The NXP 12-digit 12NC code will change its last 3 digits from '431' to '518'
- The datecode and change in 12NC can be seen on the reel packing label
- The datecode can also be seen in the 3rd line of the product's top marking

Reason

The change is necessary to pack the product in line with MSL 3.

Identification of Affected Products

Packing Labels

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Disposition of Old Products

Existing inventory will be shipped until depleted

Update Information

Due to an issue with our sales history database you may have received incomplete data. For this reason, NXP is issuing an update to the original notification to ensure sales history integrity. We apologize for any inconvenience this may have caused.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

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NXP Quality Management Team.

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Affected OPN

TJA1043ATK/0Z